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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/678,028	09/29/2003	Sameer P. Pendharker	TI-33654	9934
23494	7590	04/20/2006	EXAMINER	
TEXAS INSTRUMENTS INCORPORATED P O BOX 655474, M/S 3999 DALLAS, TX 75265			DOAN, THERESA T	
			ART UNIT	PAPER NUMBER
			2814	

DATE MAILED: 04/20/2006

Please find below and/or attached an Office communication concerning this application or proceeding.

87/

Office Action Summary	Application No.	Applicant(s)	
	10/678,028	PENDHARKER ET AL.	
	Examiner	Art Unit	
	Theresa T. Doan	2814	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 03 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 30 January 2006.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 2-15 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 2-12 is/are rejected.
- 7) ☒ Claim(s) 13-15 is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|-----------------------------------------------------------------------------------------|-----------------------------------------------------------------------------|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

1. The Amendment filed on 01/30/06 has being acknowledged. The amendments of title and drawing are accepted. By this amendment, claims 2-15 are pending in the application.

Claim Rejections - 35 USC § 103

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

3. Claims 2-3 and 5-10 are rejected under 35 U.S.C. 103(a) as being unpatentable Nishizawa (U.S. Pat. 4,404,575) as previously cited in view of Hshieh et al. (U.S. Pat. 6,657,255).

Regarding claim 2, Nishizawa (Fig. 1) discloses an integrated-circuit device, comprising: a substrate 11 (column 2, line 66), having a top surface and a bottom surface; and a vertical JFET (column 3, lines 25-29), including: a first region near the top surface (corresponding to the top portion of layer 12, see Fig. 1 labeled by the examiner below); a first and second gate regions 14 in a first region near the top surface of the substrate (corresponding to the top portion of layer 12, see Fig. 1 labeled by the examiner below and column 3, line 2), each having a top surface, a bottom surface and a side surface; the side surfaces of the first and second gate regions 14 being

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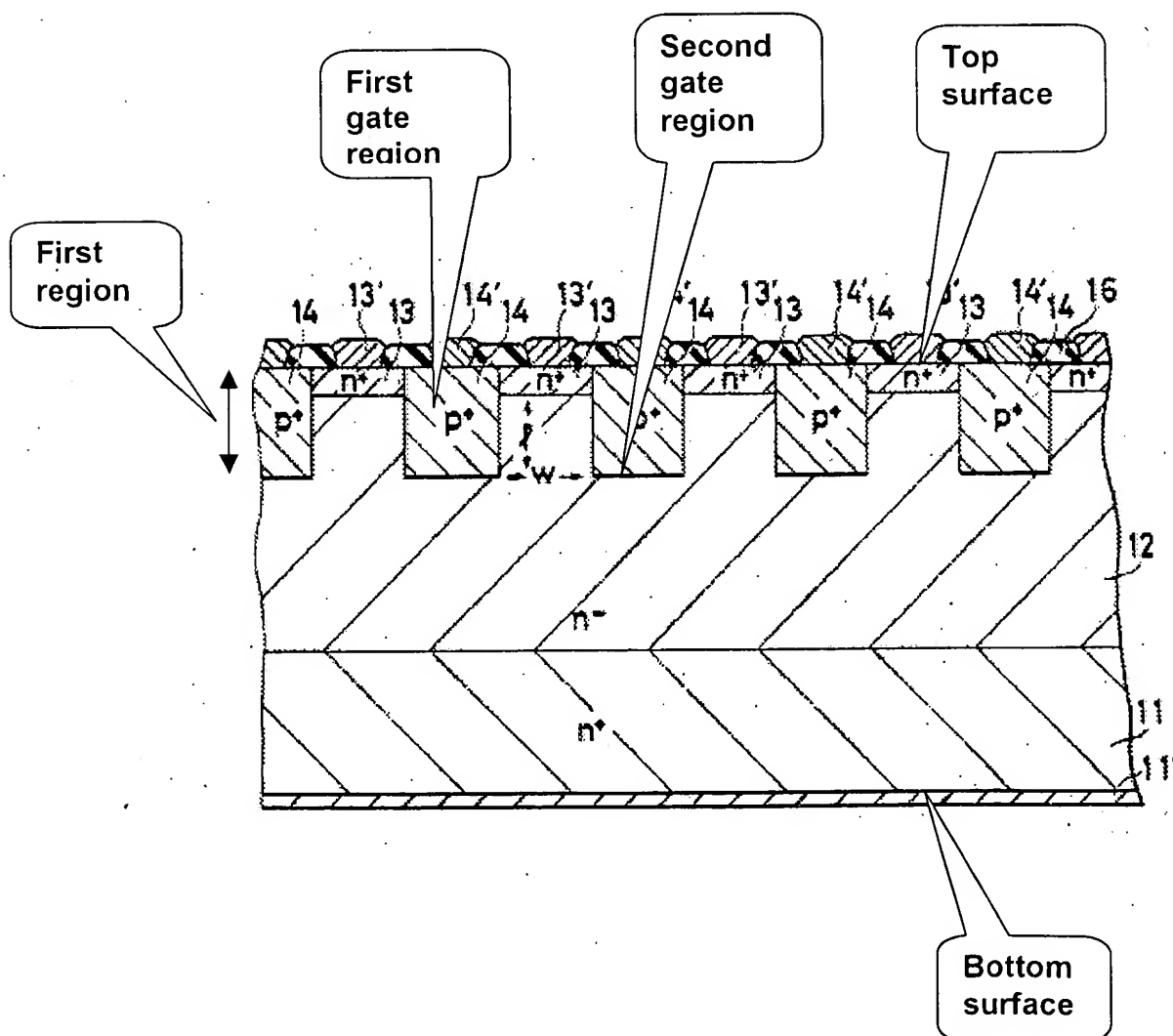
substantially parallel to each other and substantially perpendicular to the top surface of the substrate 11 (see Fig. 1 Labeled by the examiner below); the top surface of the first gate region 14 being electrically communicable to a gate terminal 14' (column 3, lines 2-5); a channel region (ℓ) in the first region, between the first and the second gate regions 14 (column 3, lines 10-15) having side surfaces adjacent to the side surfaces of the gate regions 14, a top surface, and a bottom surface; the top surface of the channel region (ℓ) electrically communicable to a source terminal 13', the bottom surface of the channel region (ℓ) electrically communicable to a drain terminal 11'; and the JFET operable to pass an electric current between the source terminal 13' and the drain terminal 11', the electric current flowing in the channel region (ℓ) in a direction vertical to the top and bottom surfaces of the channel region.

Nishizawa discloses the gate terminal, and the source terminal being near the top surface of the substrate. Nishizawa does not disclose the drain terminal also being near the top surface of the substrate.

However, Hsieh (Fig. 2A) teaches that a semiconductor device having a gate terminal 218g connected to a gate electrode 211g, a source terminal 218s connected to the source region 212, and a drain terminal 218d connected to a drain region 200 (column 4, lines 50-51). The gate terminal 218g, the source terminal 218s and the drain terminal 218d are disposed near the top surface of the substrate for improving the interconnection with other electronic components (column 4, lines 44-49). Accordingly, it would have been obvious to one having ordinary skill in the art at the time of the invention was made to modify the device structure of Nishizawa by forming the gate

terminal, the source terminal and the drain terminal being near the top surface of the substrate because by placing the drain terminal 218d on top of the device in a fashion analogous to the source terminal 218s and gate terminal 218g the ease of interconnection with other electronic components is improved, as taught by Hsieh (column 4, lines 30-49).

FIG. 1



Regarding claim 3, Nishizawa (Fig. 1) discloses that the electric current passes the channel region (1) upon a biasing voltage being applied between the source terminal 13' and the drain terminal 11' (column 5, lines 64-68 through column 6, lines 1-7), and the magnitude of the current in the channel region is controllable with a biasing voltage at the gate terminal 14' (column 3, lines 48-56).

Regarding claims 5-6, Nishizawa further discloses an n-type buried layer 12. It is noted that the process limitation (doped with antimony) would not carry patentable weight in this claim drawn to a structure, because distinct structure is not necessarily produced. In re Thorpe, 227 USPQ 964 (Fed. Cir. 1985).

Regarding claims 7-8, Nishizawa discloses that the first region of layer 12 is formed by an n-type epitaxial growth technique (column 2, lines 67-68).

Regarding claim 9, Nishizawa (Fig. 1) discloses that the substrate 11 is a bonded wafer having a bonded layer 12 formed thereon.

Regarding claim 10, Nishizawa discloses that the first gate region (14 or 24 in Fig. 6) has a pill-box shape with a substantially flat top surface and bottom surface and a side surface substantially perpendicular to the top and bottom surfaces.

Claim Rejections - 35 USC § 103

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. Claims 2-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nishizawa (U.S. Pat. 4,338,618) in view of Nishizawa (U.S. Pat. 4,404,575) as previously cited and further in view of Hsieh et al. (U.S. Pat. 6,657,255).

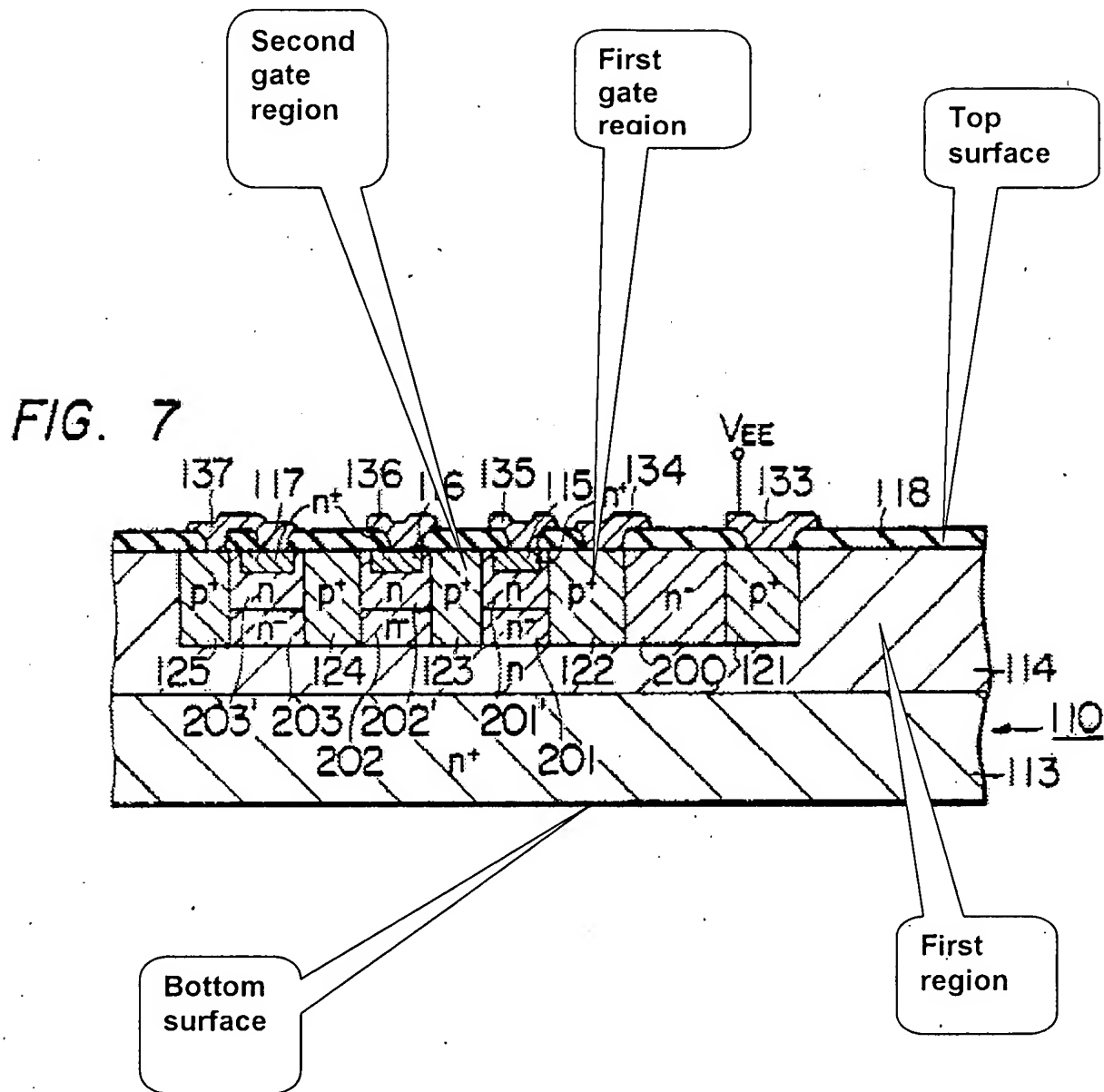
Regarding claim 2, Nishizawa '618 (Fig. 7) discloses an integrated-circuit device, comprising: a substrate 113 (column 6, lines 20-22), having a top surface and a bottom surface; and a vertical JFET (see abstract), including: a first and second gate regions (122,123) in a first region 114 near the top surface 113 (column 7, lines 9-10), each having a top surface, a bottom surface and a side surface; the side surfaces of the first and second gate regions (122,123) being substantially parallel to each other and substantially perpendicular to the top surface of the substrate 113 (see Fig. 7 Labeled by the examiner below); the top surface of the first gate region 122 being electrically communicable to a gate terminal 134; a channel region 201 in the first region 114 (column 9, lines 22-26), between the first and the second gate regions (122,123) having side surfaces adjacent to the side surfaces of the gate regions (122,123), a top surface, and a bottom surface (column 9, lines 32-34); the top surface of the channel region 201 electrically communicable to a drain terminal 135 of a drain region 115 (column 7, line 10), the bottom surface of the channel region 201 electrically communicable to a source

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terminal 113 (column 7, lines 13-15); and the JFET operable to pass an electric current between the source/drain terminal 135 and the source/drain region 113, the electric current flowing in the channel region 114 in a direction vertical to the top and bottom surfaces of the channel region 114 (column 7, lines 8-13).

Nishizawa '618 does not disclose that the drain region 115 can serve as a source region, and the source region 113 can serve as a drain region.

However, Nishizawa '575 (Fig. 8) teaches a semiconductor device having the top surface of the channel region 22 electrically communicable to a source region 23, the bottom surface of the channel region 22 electrically communicable to a drain region 21. In addition, the drain region 21 can serve as the source region and the source region 23 can serve as the drain region in order to form an inverse operation (column 7, lines 12-17). Accordingly, it would have been obvious to one having ordinary skill in the art at the time of the invention was made to modify the device structure of Nishizawa '618 by forming the source region 113 serves as a drain region and the drain region 115 serves as a source region in order to form an inverse operation, as taught by Nishizawa '575 (column 7, lines 12-17). It also would have been obvious to one having ordinary skill in the art at the time of the invention was made to modify the device structure of Nishizawa '575 by forming the gate terminal, the source terminal and the drain terminal being near the top surface of the substrate because by placing the drain terminal 218d on top of the device in a fashion analogous to the source terminal 218s and gate terminal 218g the ease of interconnection with other electronic components is improved, as taught by Hshieh (Fig. 2A, column 4, lines 30-49).



Regarding claim 3, Nishizawa '618 (Fig. 7) discloses that the electric current passes the channel region 201 upon a biasing voltage being applied between the source terminal 113 and the drain terminal 115 (column 11, lines 4-8), and the magnitude of the current in the channel region is controllable with a biasing voltage at the gate terminal 122 (column 7, lines 42-49).

Regarding claim 4, Nishizawa '618 discloses that the substrate formed under the layer 113 is a p-type silicon (not shown, see column 6, lines 25-28).

Regarding claims 5-6, Nishizawa '618 further discloses that the layer 113 is alternatively formed to be an n-type buried layer in the p-type substrate (column 6, lines 25-27). It is noted that the process limitation (doped with antimony) would not carry patentable weight in this claim drawn to a structure, because distinct structure is not necessarily produced. In re Thorpe, 227 USPQ 964 (Fed. Cir. 1985).

Regarding claims 7-8, Nishizawa '618 discloses that the first region 114 is formed by an n-type epitaxial growth technique (column 6, lines 20-25).

Regarding claim 9, Nishizawa '618 discloses that the substrate is a bonded wafer 110 (column 6, lines 20-22).

Regarding claim 10, Nishizawa '618 discloses that the first gate region 122 has a pill-box shape with a substantially flat top surface and bottom surface and a side surface substantially perpendicular to the top and bottom surfaces (see Fig. 7 above).

Regarding claim 11, Nishizawa '618 discloses that the channel region 201/202 has a ring shape enclosing the first gate region 123, a bottom surface substantially coplanar to the bottom surface of the first gate region 123 and a top surface substantially coplanar to the top surface of the first gate region 123.

Regarding claim 12, Nishizawa '618 discloses that the second gate region 124/123 has a ring shape enclosing the channel region 202, a bottom surface substantially coplanar to the bottom surface of the first gate region 123 and a top surface substantially coplanar to the top surface of the first gate region 123.

Allowable Subject Matter

6. Claims 13-15 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The prior art of record fails to disclose all the limitations recited in the above claims. Specifically, the prior art of record fails to disclose the drain plug region has a ring shape enclosing the second gate region, a bottom surface substantially coplanar to

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the bottom surface of the first gate region and a top surface substantially coplanar to the top surface of the first gate region.

Response to Arguments

7. Applicant's arguments with respect to claims 2-15 have been considered but are moot in view of the new ground(s) of rejection.

8. Applicant argues that Figs. 24A-24C of Nishizawa '575 are not JFETs but MOSFETs.

This argument is not persuasive because Figs. 24A-24C are not relied on for teaching JFETs as asserted by Applicant, but rather, Fig. 1 is relied on for teaching JFETs as claimed. Clearly, Fig. 1 of Nishizawa '575 discloses a JFET having "junction-gate" 14 (see abstract) in contact with source regions 13.

9. Applicant also argues that both patents (Nishizawa '575 and Nishizawa '618) do not disclose a JFET with a vertical channel current and having both the source and drain terminals near the top of the substrate.

This argument is not persuasive because as discussed in the ground of rejections, both Nishizawa '575 and Nishizawa '618 disclose a JFET with a vertical channel current. It would have been obvious to place the gate terminal, the source terminal and the drain terminal of Nishizawa being near the top surface of the substrate because as taught by Hsieh's Fig. 2A (newly cited reference), placing the drain

terminal 218d on top of the device in a fashion analogous to the source terminal 218s and gate terminal 218g the ease of interconnection with other electronic components is improved (column 4, lines 30-49).

10. Regarding claim 6, Applicant argues that n-type buried layer doped with antimony has a distinct structure from other doped n-type buried layer.

This argument is not persuasive because the arguments of counsel cannot take the place of evidence in the record. The attorney statements are not evidence and must be supported by an appropriate affidavit or declaration. In re Schulze, 346 F. 2d 600, 602, 145 USPQ 716, 718 (CCPA 1965). Therefore, if Applicant believes that the n-type buried layer doped with antimony has a distinct structure from other doped n-type buried layer, then Applicant is requested to support that position with facts.

The rest of applicant's arguments have been addressed to the amended claims are considered in the rejections shown above.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Theresa T. Doan whose telephone number is (571) 272-1704. The examiner can normally be reached on Monday to Friday from 7:00AM - 4:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, WAEL FAHMY can be reached on (571) 272-1705. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you

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have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

A handwritten signature in black ink, appearing to read "Theresa Doan". The signature is written in a cursive, flowing style.

Theresa Doan
April 10, 2006.

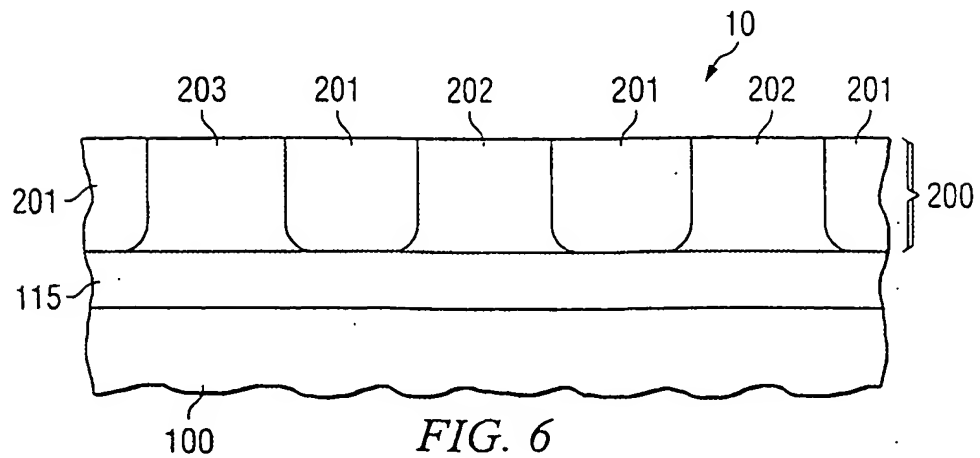
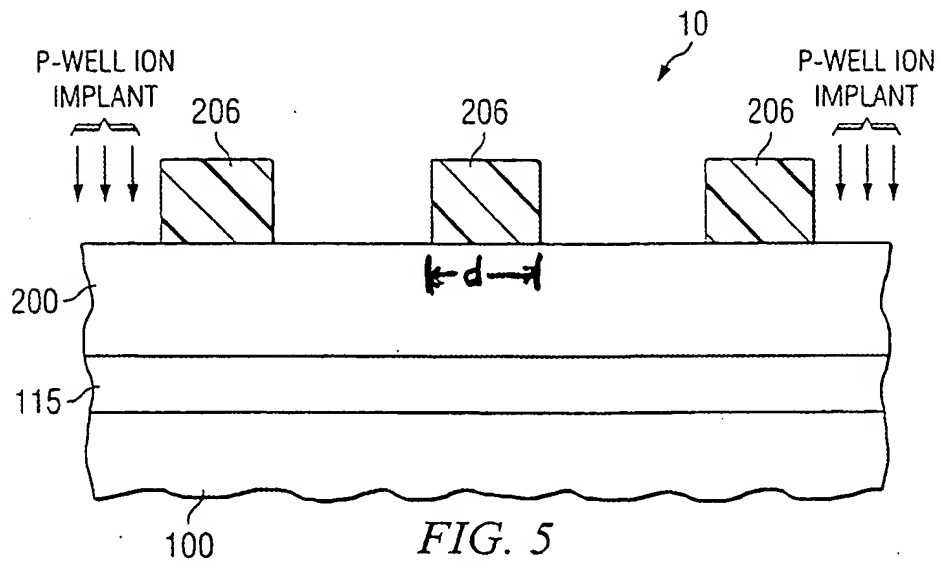
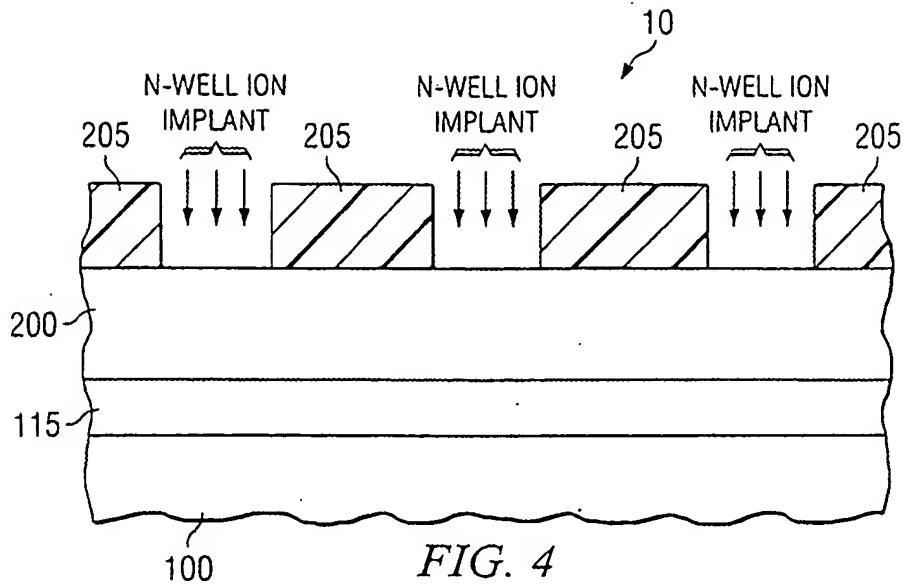


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(ST) Repl. Sheet



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